

| 版数 REV. | 年月日 DATE | DON NO. | 変更内容 DESCRIPTION | 製図 DR. | 担当 CHK. | 査閲 APPD. | 承認 APPD. |
|---------|-------------|---------|------------------|--------|---------|----------|-----------------------|
| 2 | 24.Nov.2005 | 058588 | ADDED NEW ITEMS | | K.INOUE | | <i>Ot. Hashiguchi</i> |

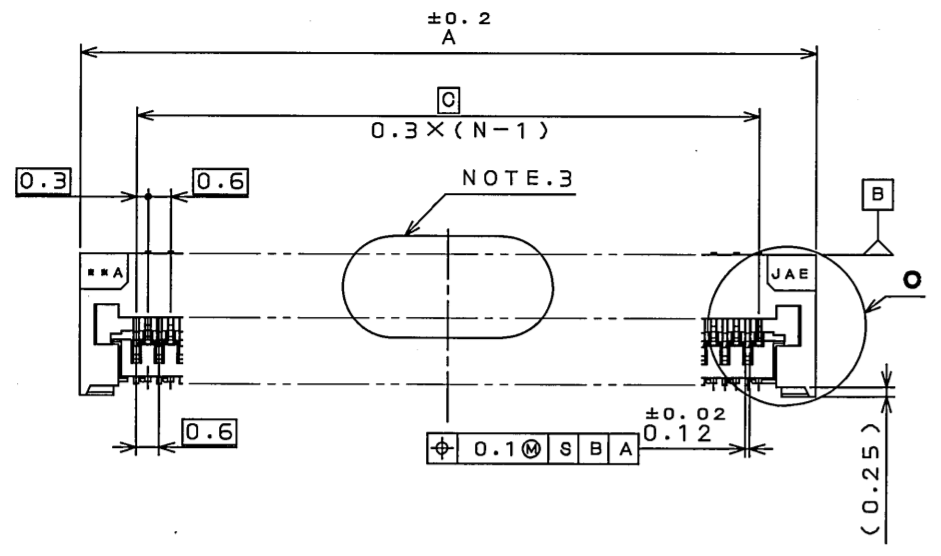
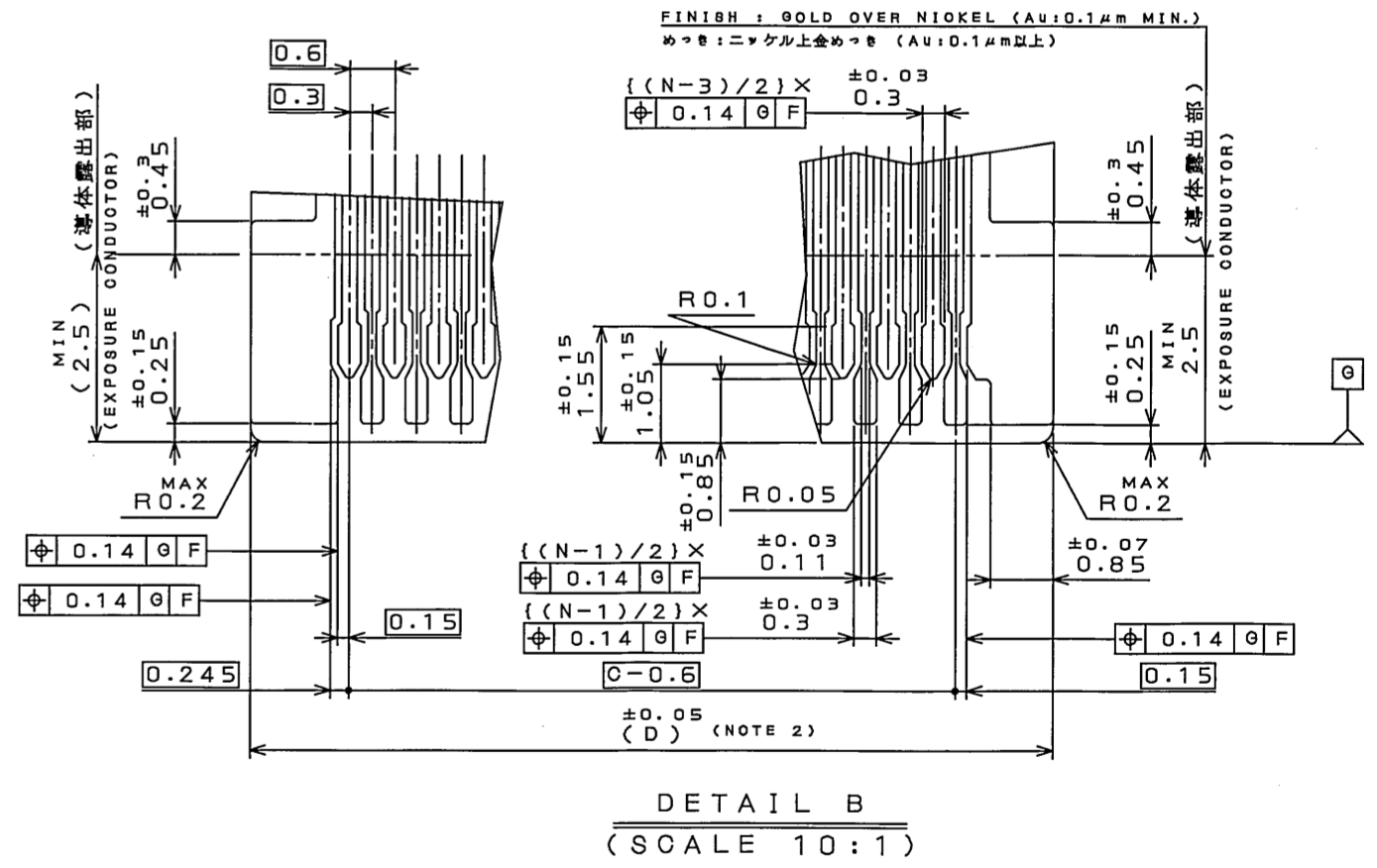
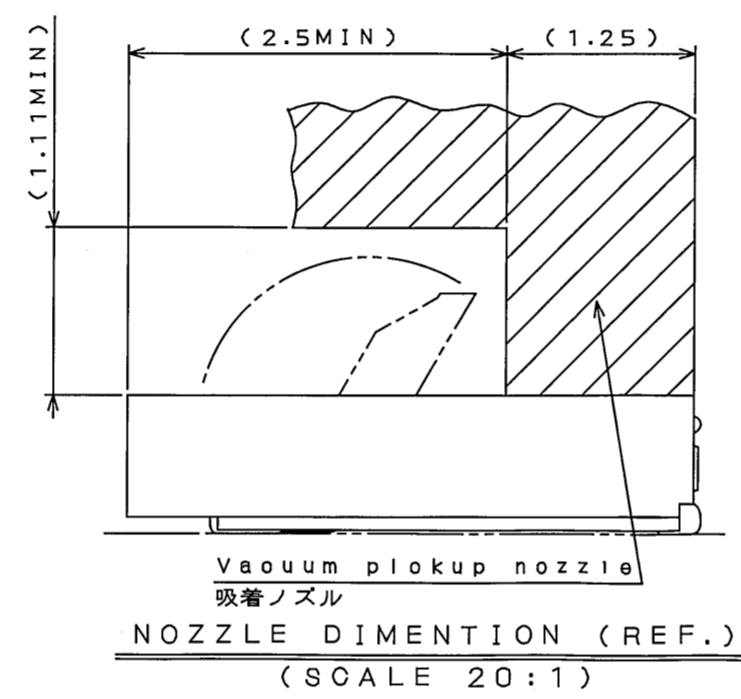
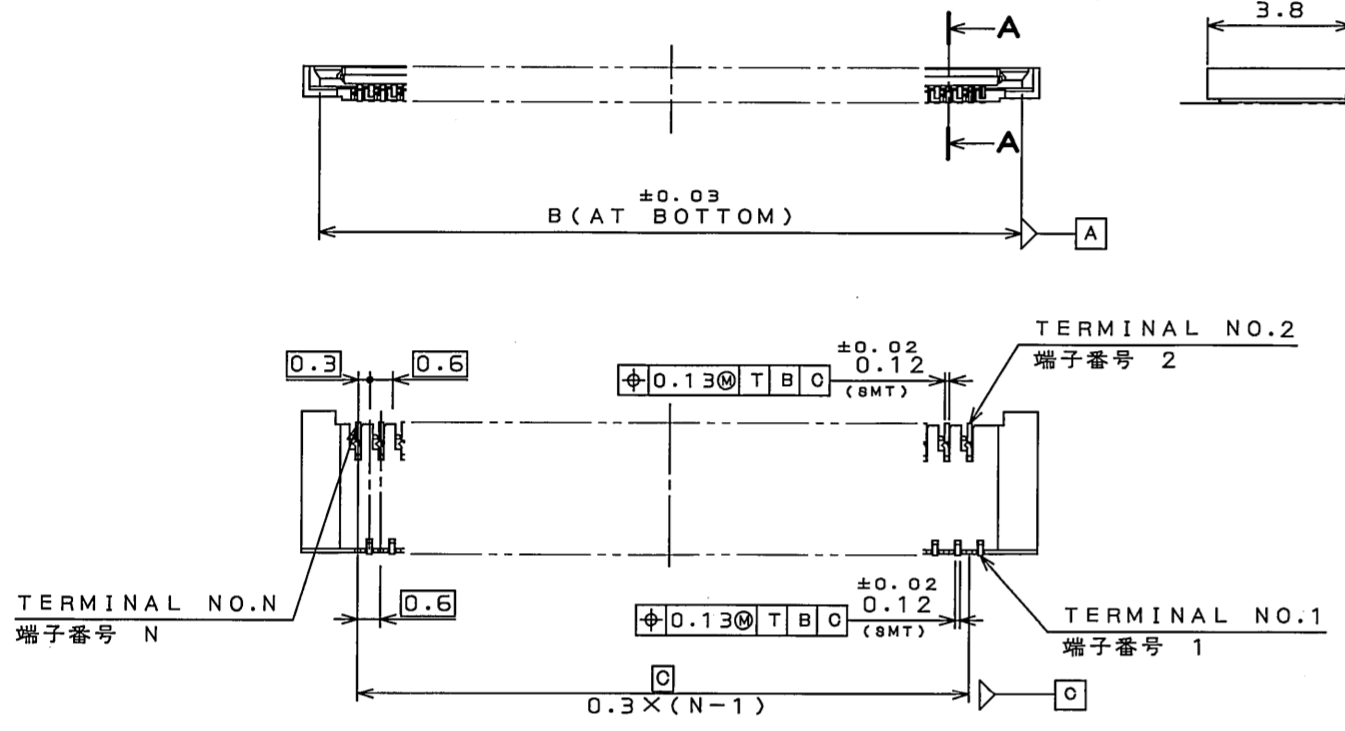
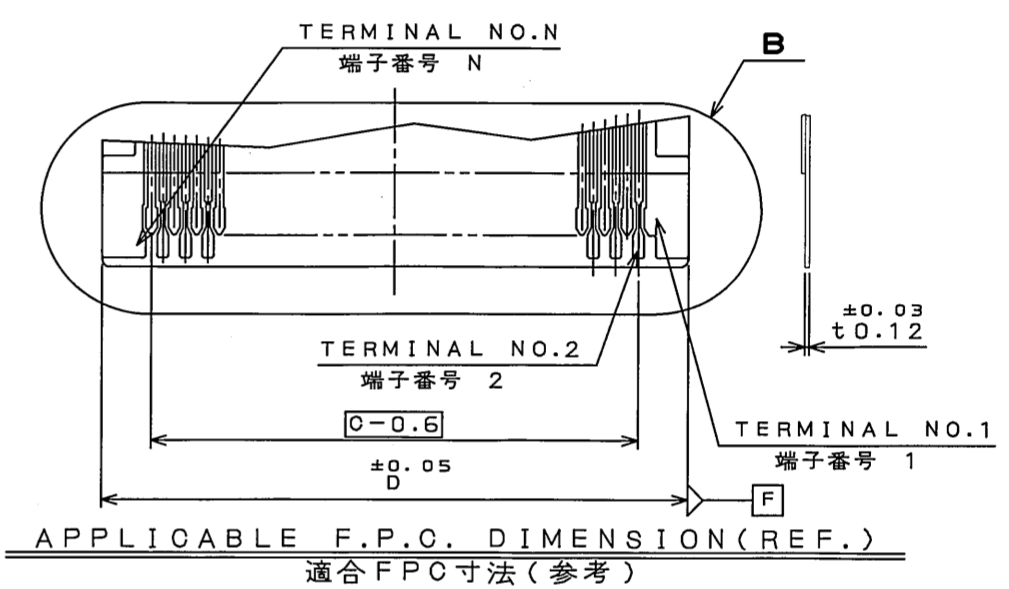
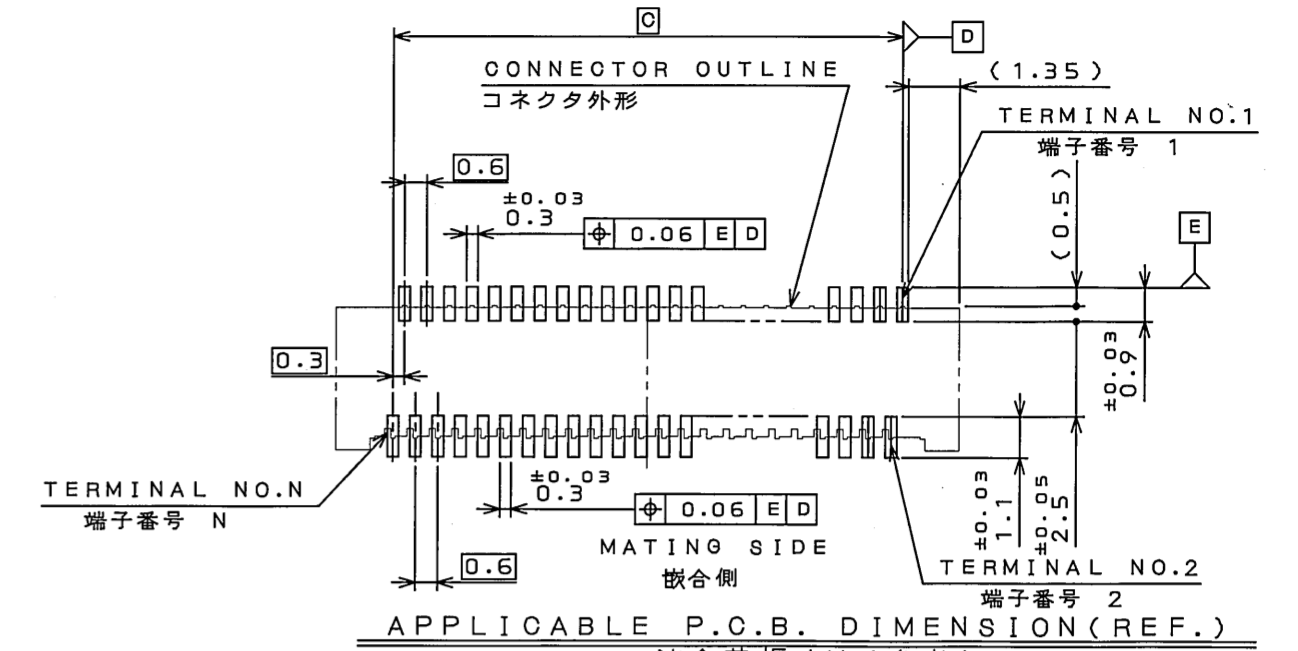


TABLE 1

| PRODUCT NO. 品名 | A | B | C | D |
|-------------------|------|-------|------|-------|
| FF02860SV1 | 20.7 | 19.81 | 17.7 | 19.74 |
| FF02850SV1 | 17.7 | 16.81 | 14.7 | 16.74 |
| FF02840SV1 | 14.7 | 13.81 | 11.7 | 13.74 |



NOTE 1. REFER TO TABLE 2 ABOUT RECOMMENDED FPC COMPOSITION.
 NOTE 2. TOLERANCE OF DIMENSION D IS RECOMMENDED TO BE ± 0.05 IN ORDER TO IMPROVE PRECISION OF PITCH POSITIONING AND CONNECTION RELIABILITY.
 NOTE 3. LOT NUMBER IS MARKED ON THE TOP CENTER PORTION OF THE CONNECTOR.

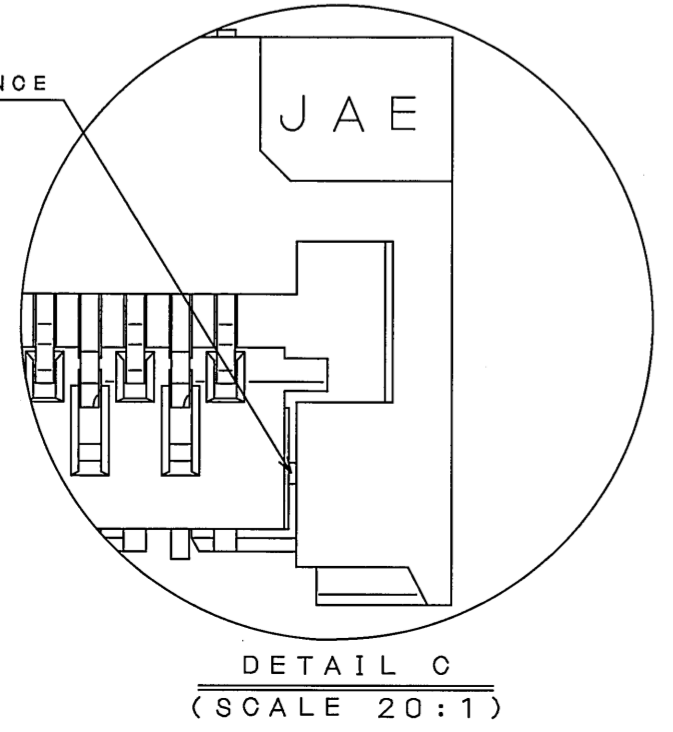
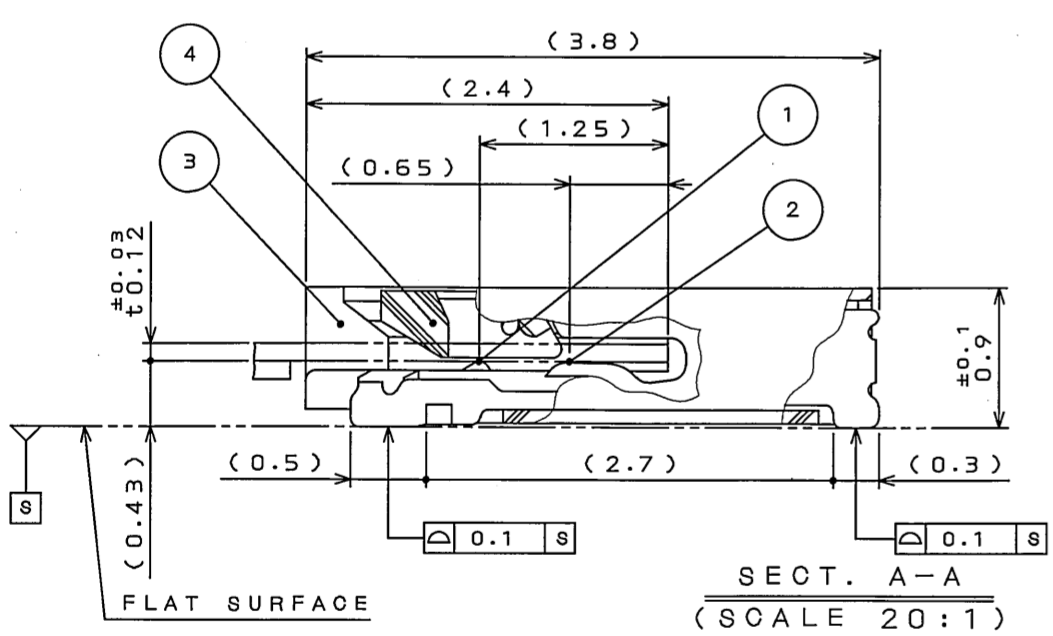
注1. 推奨FPC構成はTABLE2参照のこと。
 注2. 寸法Dはピッチ方向の位置決め精度を高め接触信頼性を高めるために ± 0.05 を推奨する。
 注3. ロット番号がコネクタ上面中央部に表記される。

TABLE 2

| COMPOSITION 層名 | | RECOMMENDED 推奨 |
|---------------------------|--------------------------------|---------------------------|
| GOLD PLATING 金めっき | ELECTROLYSIS PLATING 電解めっき | 0.1 μ m MIN |
| NICKEL PLATING ニッケルめっき | ELECTROLYSIS PLATING 電解めっき | SOFT TYPE IF AVAILABLE |
| COPPER 銅箔 | ROLLED MATERIAL 圧延銅 | NOMINAL 18 μ m MAX |
| ADHESIVE 接着剤 | THERMOSETTING ADHESIVE 熱硬化性 | NONE (RECOMMENDED) |
| BASE FILM ベースフィルム | POLYIMIDE ポリイミド | 25 μ m |
| ADHESIVE 接着剤 | THERMOSETTING ADHESIVE 熱硬化性 | 30 μ m MAX |
| REINFORCE PLATE 補強板 | POLYIMIDE ポリイミド | |

| | | | | | |
|---|------------------------------|---|---------------------|--|---|
| 4 | ACTUATOR アクチュエータ | 1 | PPS | | COLOR:BLACK/色相:黒 UL94V-0 |
| 3 | BASE INSULATOR ベースインシュレータ | 1 | LCP | | COLOR:WHITE/色相:白 UL94V-0 |
| 2 | CONTACT 2 コンタクト 2 | N | COPPER ALLOY 銅合金 | | PARTIAL GOLD OVER NICKEL(AU:0.1 μ m MIN.) ニッケル上部分金(AU:0.1 μ m 以上) |
| 1 | CONTACT 1 コンタクト 1 | N | COPPER ALLOY 銅合金 | | PARTIAL GOLD OVER NICKEL (CONTACT 2 AND 12 μ m MIN.) ニッケル上部分金 (コンタクト 2 及び 12 μ m 以上) |

| | | | | | |
|------------------------|----------------|---------------------|--------------|---------------------------|-------------|
| 符号 NO. | 名称 DESCRIPTION | 個数 QTY. | 材料 MATERIAL | 仕上 FINISH | 備考 REMARKS |
| 仕様書 (SPECIFICATION) | JAOS-10293-* | 第1版 (ORIGINAL DATE) | 14.JULI.2005 | 尺 (SCALE) | 5:1 |
| 公差 (GENERAL TOLERANCE) | | 製図 DR. | | シリーズ (SERIES) | FF02S |
| 寸法 (DIMENSION) | | 担当 CHK. | K.INOUE | 名称 (TITLE) | FF02S * SV1 |
| . ±0.8 | ° ± | 査閲 APPD. | | (EVEN NUMBER OF CONTACTS) | (偶数芯数) |
| .X ±0.4 | °X ± | 承認 APPD. | O.HASHIGUCHI | 質量 (MASS) | |
| .XX ±0.1 | | | | | |
| .XXX ± | | | | | |



DOF-0-213E (03.08)

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